Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer L1	Copper	1.40mil		
4	Dielectric 1	FR408HR	15.00mil	3.8	
5	GND Plane L2	Copper	1.40mil		
6	Dielectric 2	FR-4 High Tg	26.00mil	4.6	
7	VCC/VEE Plane L3	Copper	1.40mil		
8	Dielectric 3	FR-4 High Tg	15.00mil	4.6	
9	Bottom Layer L4	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[X] FR-408 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER _____

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____
[X] MATTE [ ] SEMI-GLOSS

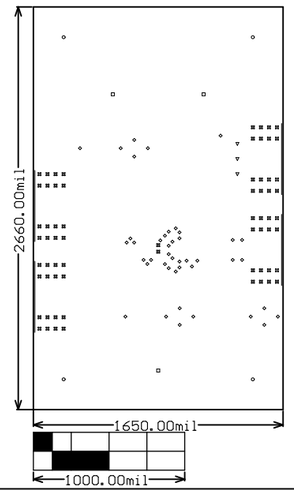
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____

ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER

ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER



32 Mil Traces on the Top Layer L1 to be 50 Ohm

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊠	66	7.87mil (0.200mm)	PTH	Round	Top Layer L1 - Bottom Layer L4	
◇	43	10.00mil (0.254mm)	PTH	Round	Top Layer L1 - Bottom Layer L4	
▽	3	40.00mil (1.016mm)	PTH	Round	Top Layer L1 - Bottom Layer L4	
○	4	125.98mil (3.200mm)	PTH	Round	Top Layer L1 - Bottom Layer L4	
□	3	270.00mil (6.858mm)	PTH	Round	Top Layer L1 - Bottom Layer L4	
	119 Total					

TEXAS INSTRUMENTS

PROJECT TITLE: OPA858DSGEVM
DESIGNED FOR: Public Release
FILE NAME: AMPS032E1.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: AMPS032	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = [illegible]ions	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 10/27/2017 9:31:32 AM	TEXAS INSTRUMENTS	

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ENGINEER:	LAYOUT BY:
Jacob Freet	Robert Holtz
SCALE: 1.00	ALTIUM DESIGNER VERSION: 17.1.5.472